

312.5 MHz LVPECL Clock Generator

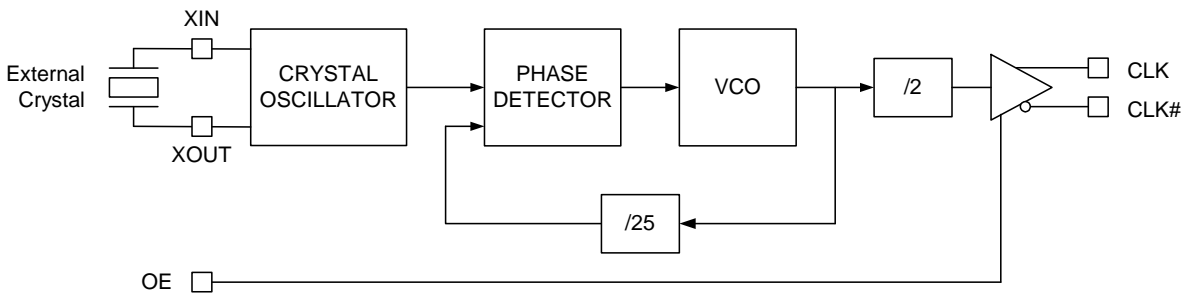
Features

- One LVPECL output pair
- Output frequency: 312.5 MHz
- External crystal frequency: 25 MHz
- Low RMS phase jitter at 312.5 MHz, using 25-MHz crystal (1.875 MHz to 20 MHz): 0.3 ps (typical)
- Pb-free 8-Pin TSSOP package
- Supply voltage: 3.3 V or 2.5 V
- Commercial and industrial temperature ranges

Functional Description

The CY2XP311 is a PLL (phase locked loop) based high-performance clock generator. It is optimized to generate 10 GB Ethernet, SONET, and other high performance clock frequencies. It also produces an output frequency that is 12.5 times the crystal frequency. It uses Cypress's low noise VCO technology to achieve 0.3 ps typical RMS phase jitter, which meets both 10 GB Ethernet and SONET jitter requirements. The CY2XP311 has a crystal oscillator interface input and one LVPECL output pair.

Logic Block Diagram



Pinouts

Figure 1. Pin Diagram - 8-Pin TSSOP



Table 1. Pin Definition - 8-Pin TSSOP

Pin Number	Pin Name	I/O Type	Description
1, 8	VDD	Power	3.3 V or 2.5 V power supply.
2	VSS	Power	Ground
3, 4	XOUT, XIN	XTAL output and input	Parallel resonant crystal interface
5	OE	CMOS input	Output enable. When HIGH, the output is enabled. When LOW, the output is high impedance
6, 7	CLK#, CLK	LVPECL output	Differential clock output

Frequency Table

Input		Output Frequency (MHz)
Crystal Frequency (MHz)	PLL Multiplier Value	
25	12.5	312.5

Absolute Maximum Conditions

Parameter	Description	Conditions	Min	Max	Unit
V _{DD}	Supply voltage	–	–0.5	4.4	V
V _{IN} ^[1]	Input voltage, DC	Relative to V _{SS}	–0.5	V _{DD} + 0.5	V
T _S	Temperature, storage	Non operating	–65	150	°C
T _J	Temperature, junction	–	–	135	°C
ESD _{HBM}	ESD protection, human body model	JEDEC STD 22-A114-B	2000	–	V
UL–94	Flammability rating	At 1/8 in.	V–0		
Θ _{JA} ^[2]	Thermal resistance, junction to ambient	0 m/s airflow	100		°C/W
		1 m/s airflow	91		
		2.5 m/s airflow	87		

Operating Conditions

Parameter	Description	Min	Max	Unit
V _{DD}	3.3 V supply voltage	3.135	3.465	V
	2.5 V supply voltage	2.375	2.625	V
T _A	Ambient temperature, commercial	0	70	°C
	Ambient temperature, industrial	–40	85	°C
T _{PU}	Power up time for all V _{DD} to reach minimum specified voltage (ensure power ramps is monotonic)	0.05	500	ms

Notes

1. The voltage on any input or I/O pin cannot exceed the power pin during power up.
2. Simulated using Apache Sentinel TI software. The board is derived from the JEDEC multilayer standard. It measures 76 x 114 x 1.6 mm and has 4-layers of copper (2/1/1/2 oz.). The internal layers are 100% copper planes, while the top and bottom layers have 50% metalization. No vias are included in the model.

DC Electrical Characteristics

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
I _{DD}	Operating supply current with output unterminated	V _{DD} = 3.465 V, OE = V _{DD} , output unterminated	–	–	125	mA
		V _{DD} = 2.625 V, OE = V _{DD} , output unterminated	–	–	120	mA
I _{DDT}	Operating supply current with output terminated	V _{DD} = 3.465 V, OE = V _{DD} , output terminated	–	–	150	mA
		V _{DD} = 2.625 V, OE = V _{DD} , output terminated	–	–	145	mA
V _{OH}	LVPECL output high voltage	V _{DD} = 3.3 V or 2.5 V, R _{TERM} = 50 Ω to V _{DD} – 2.0V	V _{DD} – 1.15	–	V _{DD} – 0.75	V
V _{OL}	LVPECL output low voltage	V _{DD} = 3.3 V or 2.5 V, R _{TERM} = 50 Ω to V _{DD} – 2.0V	V _{DD} – 2.0	–	V _{DD} – 1.625	V
V _{OD1}	LVPECL peak-to-peak output voltage swing	V _{DD} = 3.3 V or 2.5 V, R _{TERM} = 50 Ω to V _{DD} – 2.0V	600	–	1000	mV
V _{OD2}	LVPECL output voltage swing (V _{OH} – V _{OL})	V _{DD} = 2.5 V, R _{TERM} = 50 Ω to V _{DD} – 1.5 V	500	–	1000	mV
V _{OCM}	LVPECL output common mode voltage (V _{OH} + V _{OL})/2	V _{DD} = 2.5 V, R _{TERM} = 50 Ω to V _{DD} – 1.5 V	1.2	–	–	V
I _{OZ}	LVPECL output leakage current	Output off, OE = V _{SS}	–35	–	35	μA
V _{IH}	Input high voltage, OE Pin	–	0.7*V _{DD}	–	V _{DD} +0.3	V
V _{IL}	Input low voltage, OE Pin	–	–0.3	–	0.3*V _{DD}	V
I _{IH}	Input high current, OE Pin	OE = V _{DD}	–	–	115	μA
I _{IL}	Input low current, OE Pin	OE = V _{SS}	–50	–	–	μA
C _{IN} ^[5]	Input capacitance, OE Pin	–	–	15	–	pF
C _{INX} ^[5]	Pin capacitance, XIN & XOUT	–	–	4.5	–	pF

AC Electrical Characteristics^[5]

Parameter	Description	Conditions	Min	Typ	Max	Unit
F _{OUT}	Output frequency		–	312.5	–	MHz
T _R , T _F ^[3]	Output rise or fall time	20% to 80% of full output swing	–	0.5	1.0	ns
T _{Jitter(φ)} ^[6]	RMS phase jitter (random)	312.5 MHz, (1.875 to 20 MHz)	–	0.3	–	ps
T _{DC} ^[7]	Output duty cycle	Measured at zero crossing point	45	–	55	%
T _{OHZ}	Output disable time	Time from falling edge on OE to stopped outputs (Asynchronous)	–	–	100	ns
T _{OE}	Output enable time	Time from rising edge on OE to outputs at a valid frequency (Asynchronous)	–	–	100	ns
T _{LOCK}	Startup time	Time for CLK to reach valid frequency measured from the time V _{DD} = V _{DD} (min.)	–	–	5	ms

Recommended Crystal Specifications^[4]

Parameter	Description	Min	Max	Unit
Mode	Mode of Oscillation	Fundamental		–
F	Frequency	25	25	MHz
ESR	Equivalent Series Resistance	–	50	Ω
C _S	Shunt Capacitance	–	7	pF

Notes

3. Refer to Figure 5 on page 4.
4. Characterized using an 18 pF parallel resonant crystal.
5. Not 100% tested, guaranteed by design and characterization.
6. Refer to Figure 6 on page 5.
7. Refer to Figure 7 on page 5.

Parameter Measurements

Figure 2. 3.3 V Output Load AC Test Circuit

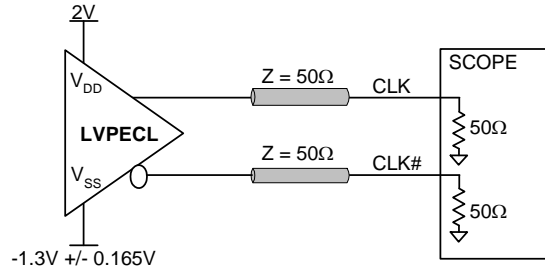


Figure 3. 2.5 V Output Load AC Test Circuit

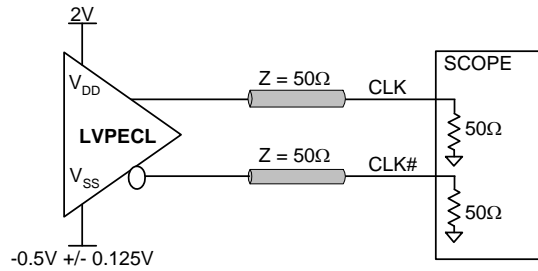


Figure 4. Output DC Parameters

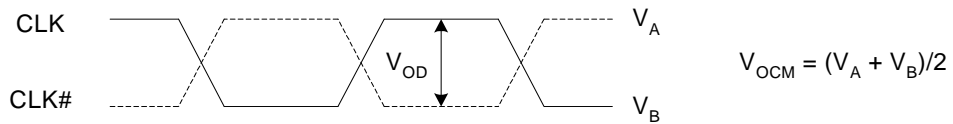


Figure 5. Output Rise and Fall Time

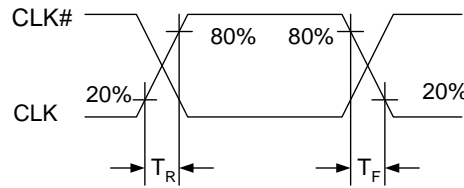


Figure 6. RMS Phase Jitter

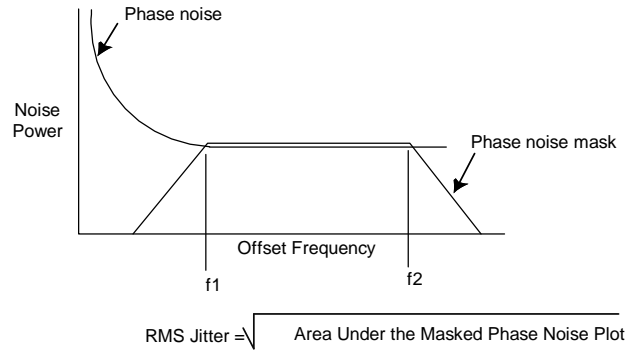


Figure 7. Output Duty Cycle

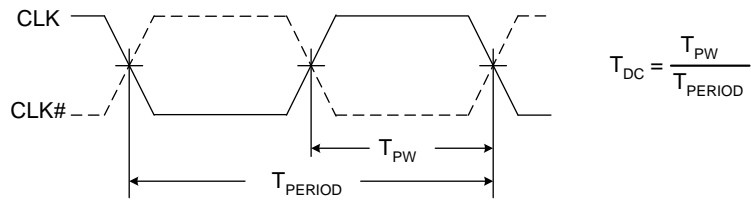
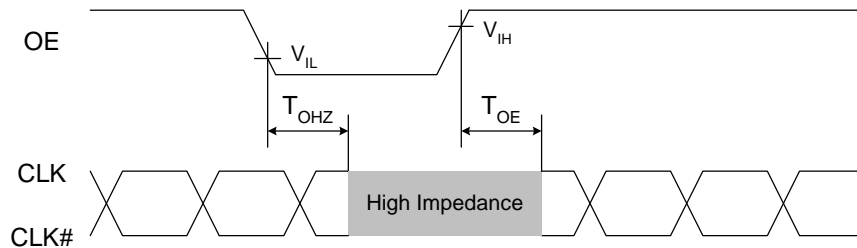


Figure 8. Output Enable Timing



Application Information

Power Supply Filtering Techniques

As in any high speed analog circuitry, noise at the power supply pins can degrade performance. To achieve optimum jitter performance, use good power supply isolation practices. Figure 9 illustrates a typical filtering scheme. 0.01 to 0.1 μF ceramic chip capacitors are located close to the VDD pins to provide a short and low impedance AC path to ground. A 1 to 10 μF ceramic or tantalum capacitor is located in the general vicinity of this device and may be shared with other devices. An acceptable alternative power supply configuration is shown in Figure 10.

Figure 9. Power Supply Filtering

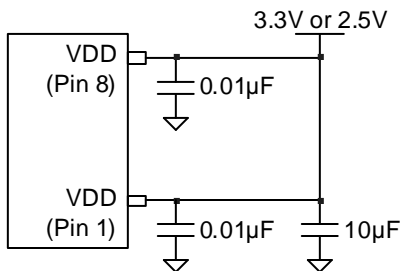
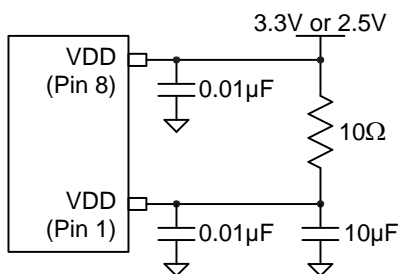


Figure 10. Alternative Power Supply Filtering

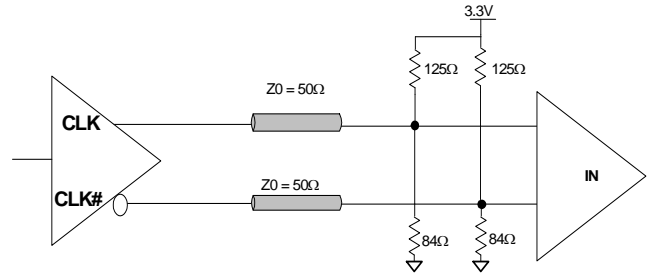


Termination for LVPECL Output

The CY2XP311 implements its LVPECL driver with a current steering design. For proper operation, it requires a 50 ohm dc termination on each of the two output signals. For 3.3 V operation, this data sheet specifies output levels for termination to $V_{DD}-2.0\text{ V}$. This same termination voltage can also be used for $V_{DD} = 2.5\text{ V}$ operation, or it can be terminated to $V_{DD}-1.5\text{ V}$. Note that it is also possible to terminate with 50 ohms to ground

(V_{SS}), but the high and low signal levels differ from the data sheet values. Termination resistors are best located close to the destination device. To avoid reflections, trace characteristic impedance (Z_0) should match the termination impedance. Figure 11 shows a standard termination scheme.

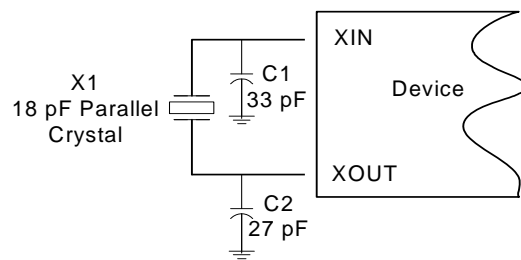
Figure 11. LVPECL Output Termination



Crystal Input Interface

The CY2XP311 is characterized with 18 pF parallel resonant crystals. The capacitor values shown in Figure 12 are determined using a 25 MHz 18 pF parallel resonant crystal and are chosen to minimize the ppm error. Note that the optimal values for C1 and C2 depend on the parasitic trace capacitance and are therefore layout dependent.

Figure 12. Crystal Input Interface

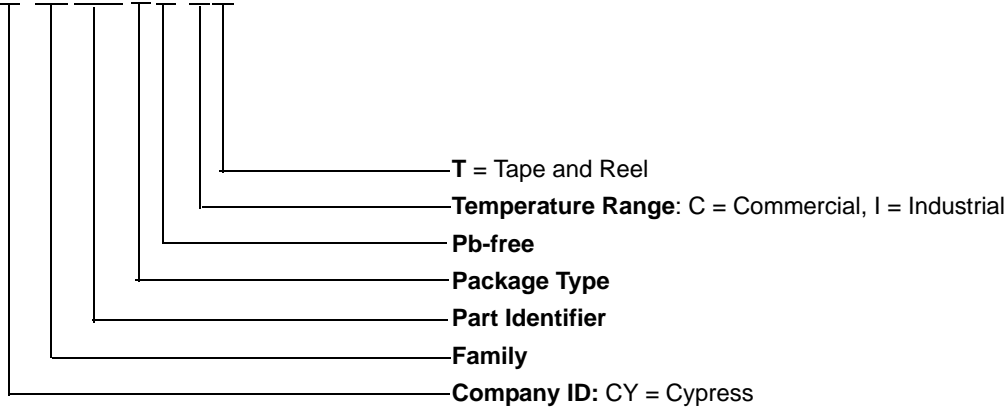


Ordering Information

Part Number	Package Type	Product Flow
CY2XP311ZXC	8-Pin TSSOP	Commercial, 0 °C to 70 °C
CY2XP311ZXCT	8-Pin TSSOP - Tape and Reel	Commercial, 0 °C to 70 °C
CY2XP311ZXI	8-Pin TSSOP	Industrial, -40 °C to 85 °C
CY2XP311ZXIT	8-Pin TSSOP - Tape and Reel	Industrial, -40 °C to 85 °C

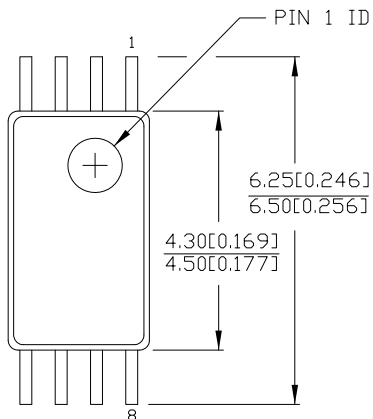
Ordering Code Definitions

CY xx xxxx Z X C/I T



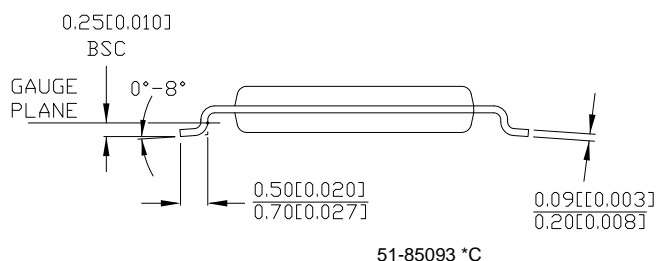
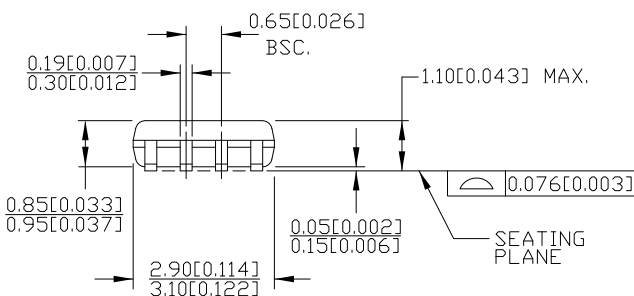
Package Drawing and Dimensions

Figure 13. 8-Pin Thin Shrunk Small Outline Package (4.40 MM Body) Z8



DIMENSIONS IN MM[INCHES] MIN. MAX.
REFERENCE JEDEC MO-153

PART #	
Z08.173	STANDARD PKG.
ZZ08.173	LEAD FREE PKG.



Acronyms

Acronym	Description
CLKOUT	Clock output
CMOS	Complementary metal oxide semiconductor
DPM	Die pick map
EPROM	Erasable programmable read only memory
LVDS	Low-voltage differential signaling
LVPECL	Low voltage positive emitter coupled logic
NTSC	National television system committee
OE	Output enable
PAL	Phase alternate line
PD	Power down
PLL	Phase locked loop
PPM	Parts per million
TTL	Transistor transistor logic

Document Conventions

Units of Measures

Symbol	Unit of Measure
°C	degrees Celsius
kHz	kilohertz
kΩ	kilohms
MHz	megahertz
MΩ	megaohms
μA	microamperes
μs	microseconds
μV	microvolts
μVrms	microvolts root-mean-square
mA	milliamperes
mm	millimeters
ms	milliseconds
mV	millivolts
nA	nanoamperes
ns	nanoseconds
nV	nanovolts
Ω	ohms

Document History Page

Document Title: CY2XP311 312.5 MHz LVPECL Clock Generator Document Number: 001-59931				
Rev.	ECN No.	Submission Date	Orig. of Change	Description of Change
**	2897143	3/22/2010	KVM	New data sheet
*A	2915328	04/16/2010	KVM	Changed status from Preliminary to Final
*B	3201150	03/21/2011	BASH	Added Ordering Code Definition, Acronyms and Document Conventions. Updated the package diagram.

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